

# 74HC540; 74HCT540

Octal buffer/line driver; 3-state; inverting

Rev. 3 — 21 January 2013

Product data sheet

## 1. General description

The 74HC540; 74HCT540 is an 8-bit inverting buffer/line driver with 3-state outputs. The device features two output enables ( $\overline{OE}1$  and  $\overline{OE}2$ ). A HIGH on  $\overline{OE}n$  causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## 2. Features and benefits

- Inverting outputs
- Complies with JEDEC standard no. 7A
- Input levels:
  - ◆ For 74HC540: CMOS level
  - ◆ For 74HCT540: TTL level
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

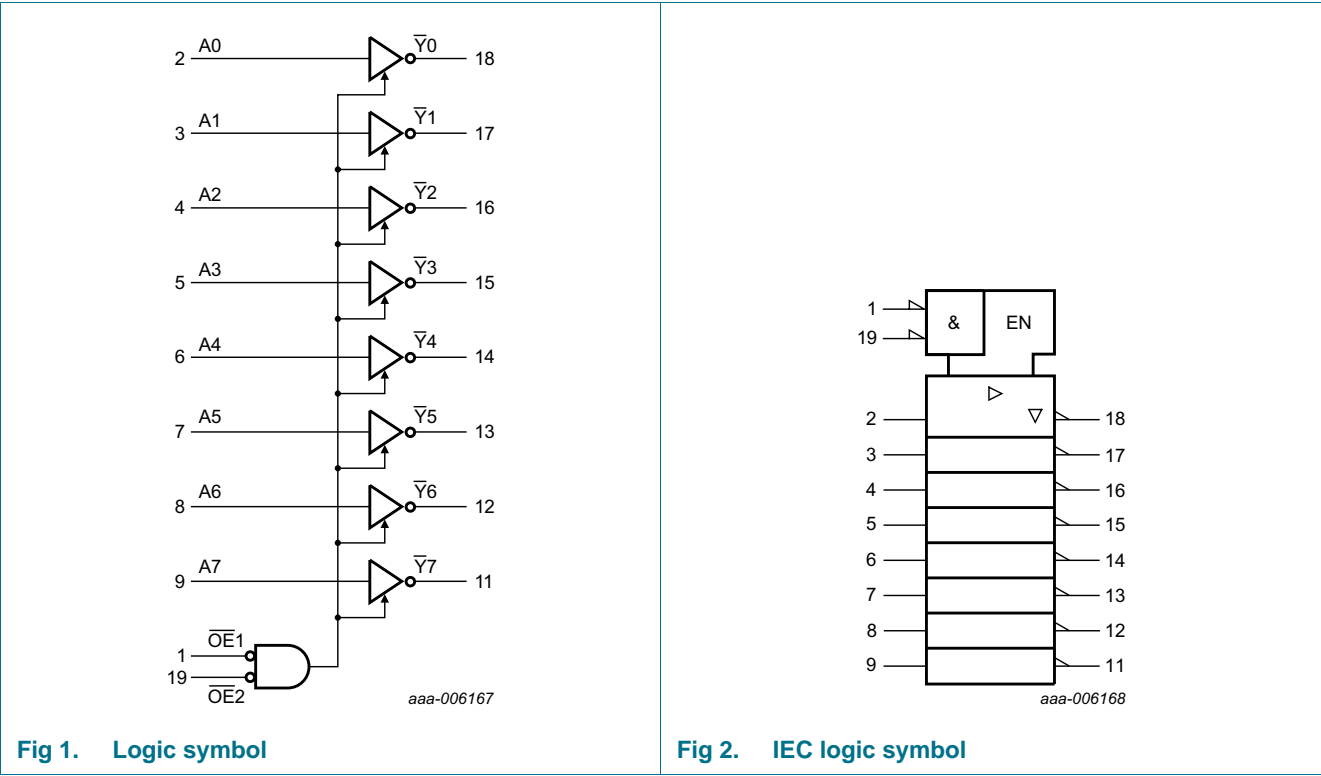
## 3. Ordering information

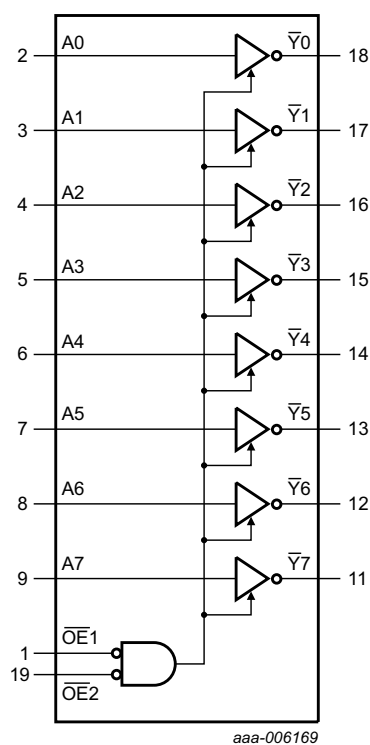
Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC540N 74HCT540N	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DIP20	plastic dual in-line package; 20 leads (300 mil)	SOT146-1
74HC540D 74HCT540D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74HC540DB 74HCT540DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1



4. Functional diagram





**Fig 3. Functional diagram**

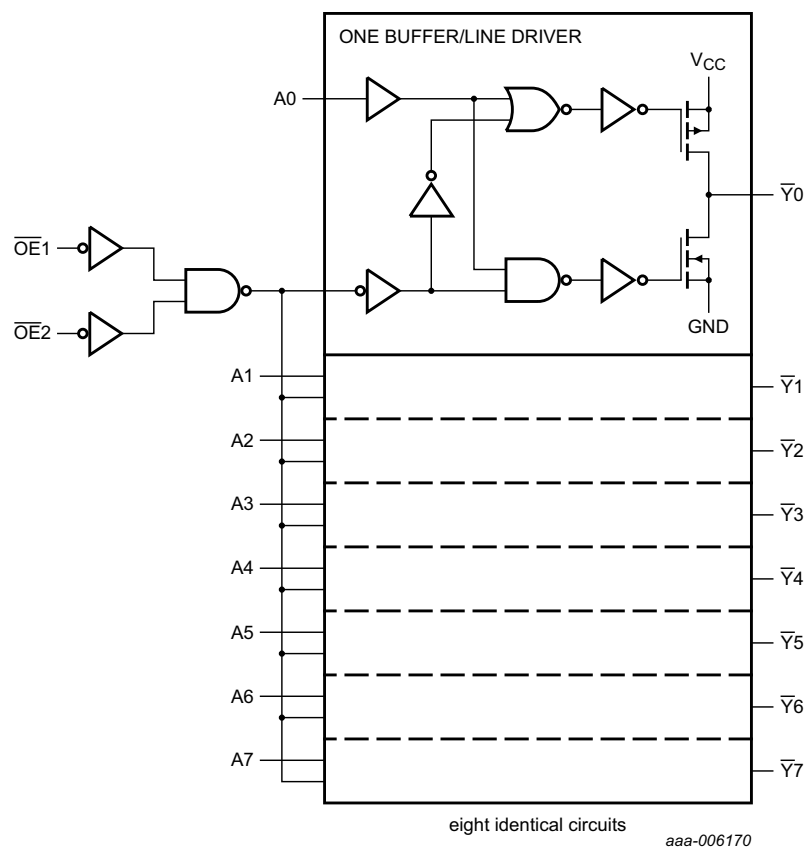


Fig 4. Logic diagram

## 5. Pinning information

### 5.1 Pinning

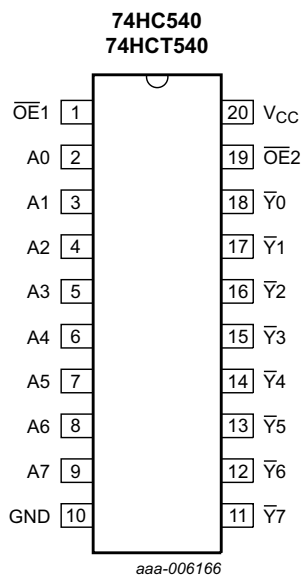


Fig 5. Pin configuration DIP20, SO20 and SSOP20

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}1$	1	output enable input (active LOW)
A0 to A7	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
$\overline{Y}0$ to $\overline{Y}7$	18, 17, 16, 15, 14, 13, 12, 11	data output
$\overline{OE}2$	19	output enable input (active LOW)
$V_{CC}$	20	supply voltage

## 6. Functional description

Table 3. Functional table<sup>[1]</sup>

Control		Input	Output
$\overline{OE}1$	$\overline{OE}2$	$A_n$	$\overline{Y}_n$
L	L	L	H
L	L	H	L
X	H	X	Z
H	X	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	[1] -	$\pm 20$	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	[1] -	$\pm 20$	mA
$I_O$	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	$\pm 35$	mA
$I_{CC}$	supply current		-	70	mA
$I_{GND}$	ground current		-70	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation		[2]		
	DIP20		-	750	mW
	SO20, SSOP20		-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP20 packages: above 70 °C the value of  $P_{tot}$  derates linearly with 12 mW/K.

For SO20 packages: above 70 °C the value of  $P_{tot}$  derates linearly with 8 mW/K.

For SSOP20 packages: above 60 °C the value of  $P_{tot}$  derates linearly with 5.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC540			74HCT540			Unit
			Min	Typ	Max	Min	Typ	Max	
$V_{CC}$	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	-	-	-	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	-	-	-	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = –40 °C to +85 °C		T <sub>amb</sub> = –40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC540										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = –20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = –20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = –20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = –6.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = –7.8 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 7.8 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	per input pin; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V; I <sub>O</sub> = 0 A	-	±0.5	-	±5.0	-	±10	-	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT540										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = –20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = –6.0 mA	3.98	4.32	-	3.84	-	3.7	-	V

**Table 6.** Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = –40 °C to +85 °C		T <sub>amb</sub> = –40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 µA;	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA;	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I <sub>OZ</sub>	OFF-state output current	per input pin; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V; I <sub>O</sub> = 0 A	-	-	±0.5	-	±5.0	-	±10	µA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	µA
ΔI <sub>CC</sub>	additional supply current	per input pin; I <sub>O</sub> = 0 A; V <sub>I</sub> = V <sub>CC</sub> – 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V								
		An input	-	140	504	-	630	-	686	µA
		$\overline{\text{OE}}1$ input	-	150	540	-	675	-	735	µA
		$\overline{\text{OE}}2$ input	-	100	360	-	450	-	490	µA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7.** Dynamic characteristicsGND = 0 V; C<sub>L</sub> = 50 pF; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = −40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
74HC540								
t <sub>pd</sub>	propagation delay	An to Y <sub>n</sub> ; see <a href="#">Figure 6</a>	[1]					
		V <sub>CC</sub> = 2.0 V	-	30	100	125	150	ns
		V <sub>CC</sub> = 4.5 V	-	11	20	25	30	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	9	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	-	9	17	21	26	ns
t <sub>en</sub>	enable time	$\overline{\text{OEn}}$ to Y <sub>n</sub> ; see <a href="#">Figure 7</a>	[1]					
		V <sub>CC</sub> = 2.0 V	-	52	160	200	240	ns
		V <sub>CC</sub> = 4.5 V	-	19	32	40	48	ns
		V <sub>CC</sub> = 6.0 V	-	15	27	34	41	ns
t <sub>dis</sub>	disable time	$\overline{\text{OEn}}$ to Y <sub>n</sub> ; see <a href="#">Figure 7</a>	[1]					
		V <sub>CC</sub> = 2.0 V	-	61	160	200	240	ns
		V <sub>CC</sub> = 4.5 V	-	22	32	40	48	ns
		V <sub>CC</sub> = 6.0 V	-	18	27	34	41	ns



**Table 7. Dynamic characteristics**GND = 0 V;  $C_L = 50$  pF; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = –40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
t <sub>t</sub>	transition time	see <a href="#">Figure 6</a> <a href="#">[2]</a>						
		V <sub>CC</sub> = 2.0 V	-	14	60	75	90	ns
		V <sub>CC</sub> = 4.5 V	-	5	12	15	18	ns
		V <sub>CC</sub> = 6.0 V	-	4	10	13	15	ns
C <sub>PD</sub>	power dissipation capacitance	per package; V <sub>I</sub> = GND to V <sub>CC</sub> <a href="#">[3]</a>	-	39	-	-	-	pF

**74HCT540**

t <sub>pd</sub>	propagation delay	An to Yn; see <a href="#">Figure 6</a> <a href="#">[1]</a>						
		V <sub>CC</sub> = 4.5 V	-	13	24	30	36	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	11	-	-	-	ns
t <sub>en</sub>	enable time	$\overline{\text{OEn}}$ to Yn; see <a href="#">Figure 7</a> <a href="#">[1]</a>						
		V <sub>CC</sub> = 4.5 V	-	22	35	44	53	ns
t <sub>dis</sub>	disable time	$\overline{\text{OEn}}$ to Yn; see <a href="#">Figure 7</a> <a href="#">[1]</a>						
		V <sub>CC</sub> = 4.5 V	-	23	35	44	53	ns
t <sub>t</sub>	transition time	V <sub>CC</sub> = 4.5 V; see <a href="#">Figure 6</a> <a href="#">[2]</a>	-	5	12	15	18	ns
C <sub>PD</sub>	power dissipation capacitance	per package; V <sub>I</sub> = GND to V <sub>CC</sub> – 1.5 V <a href="#">[3]</a>	-	44	-	-	-	pF

- [1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.  
t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.  
t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.

- [2] t<sub>t</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.

- [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

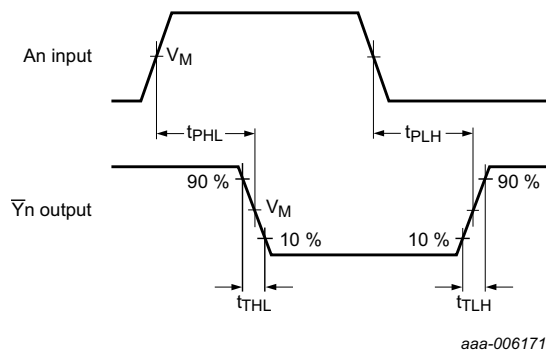
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

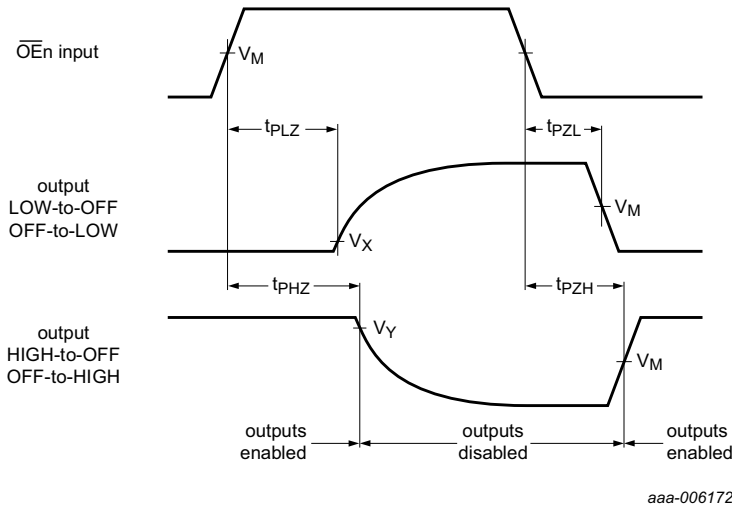
$\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

11. Waveforms



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. Input to output propagation delays**



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. 3-state enable and disable times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC540	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT540	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$

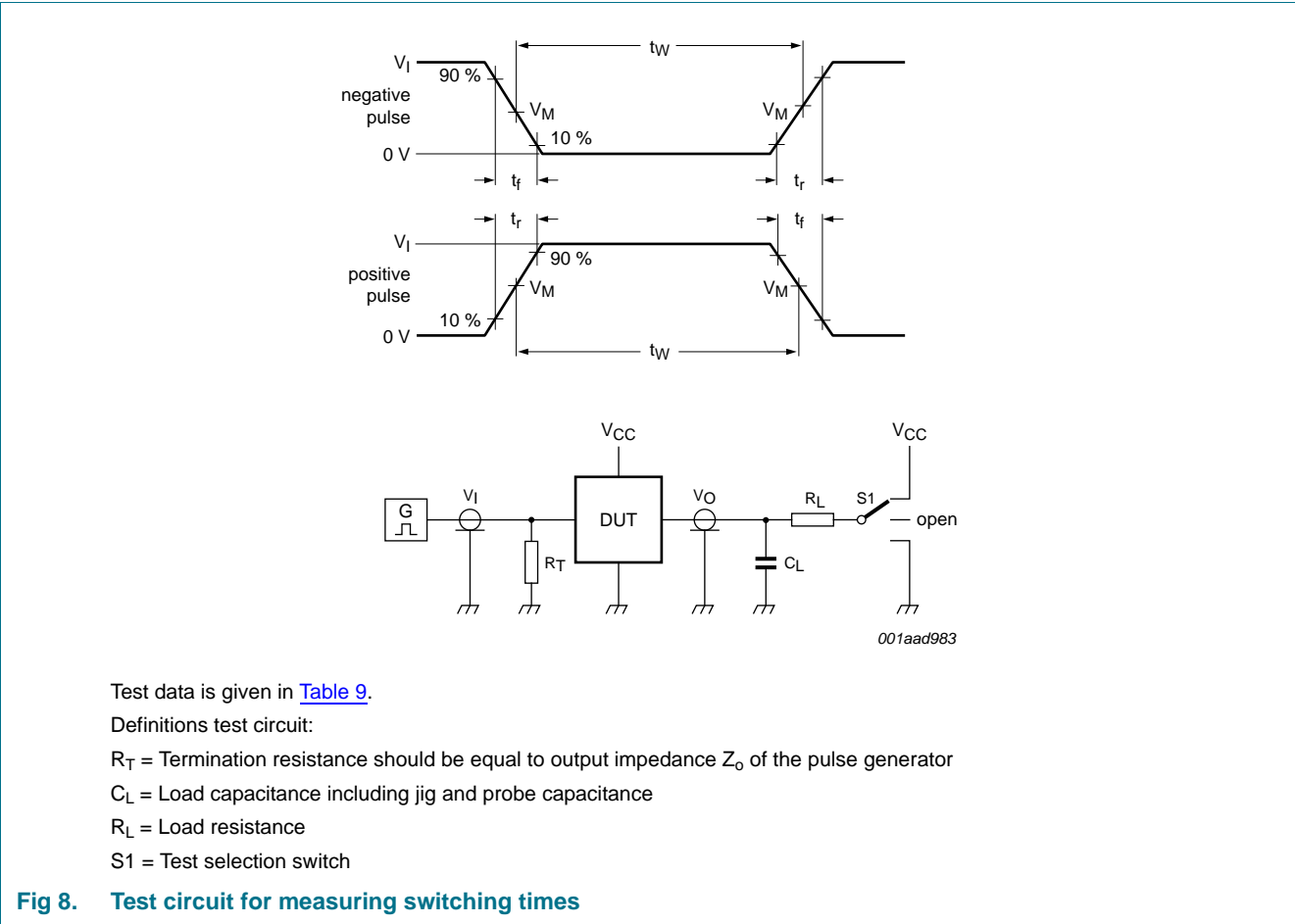


Table 9. Test data

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC540	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT540	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

12. Package outline

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1

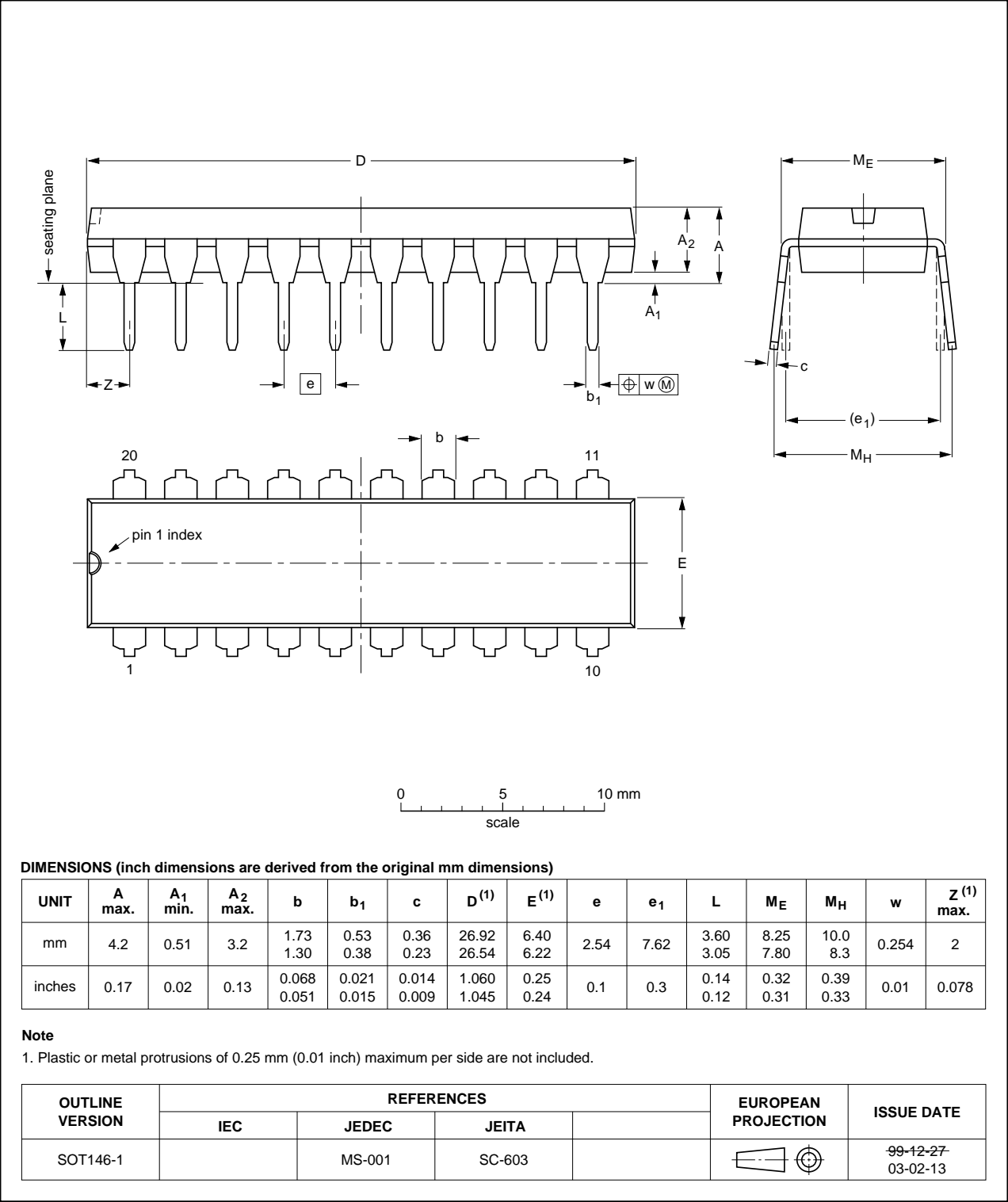
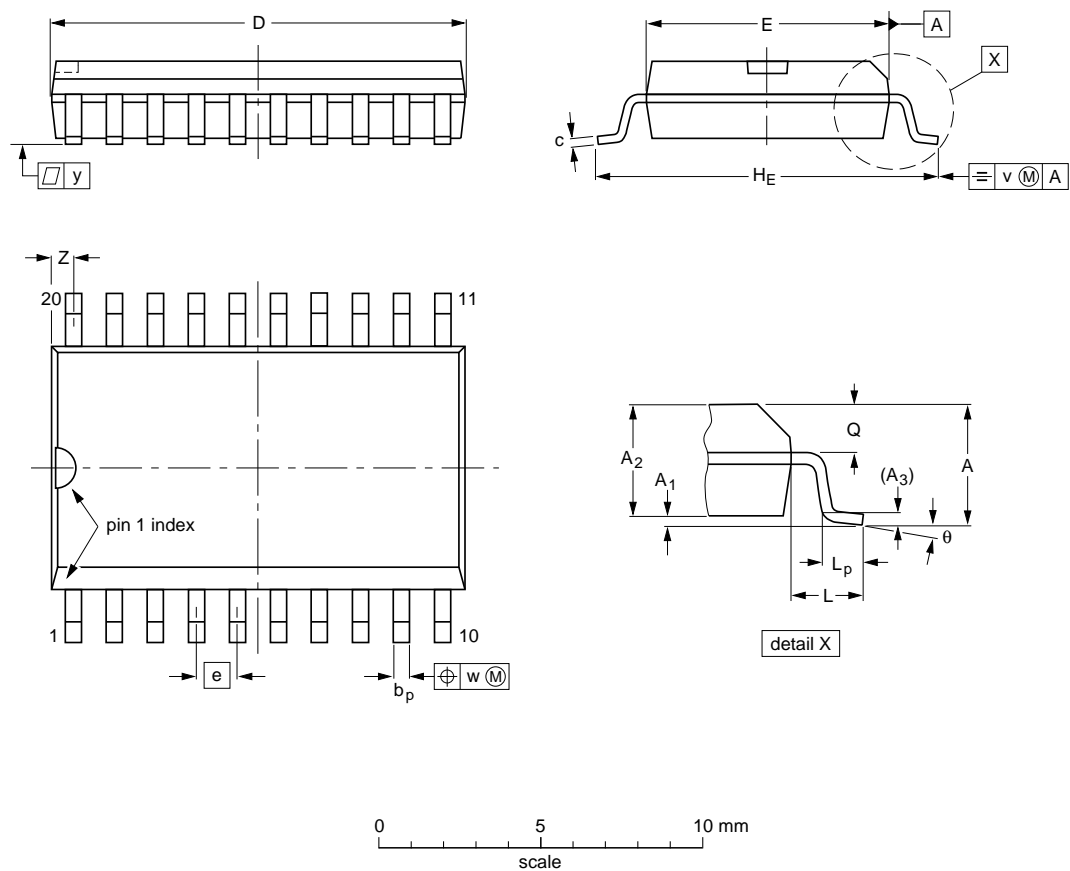


Fig 9. Package outline SOT146-1 (DIP20)

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				99-12-27 03-02-19

Fig 10. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

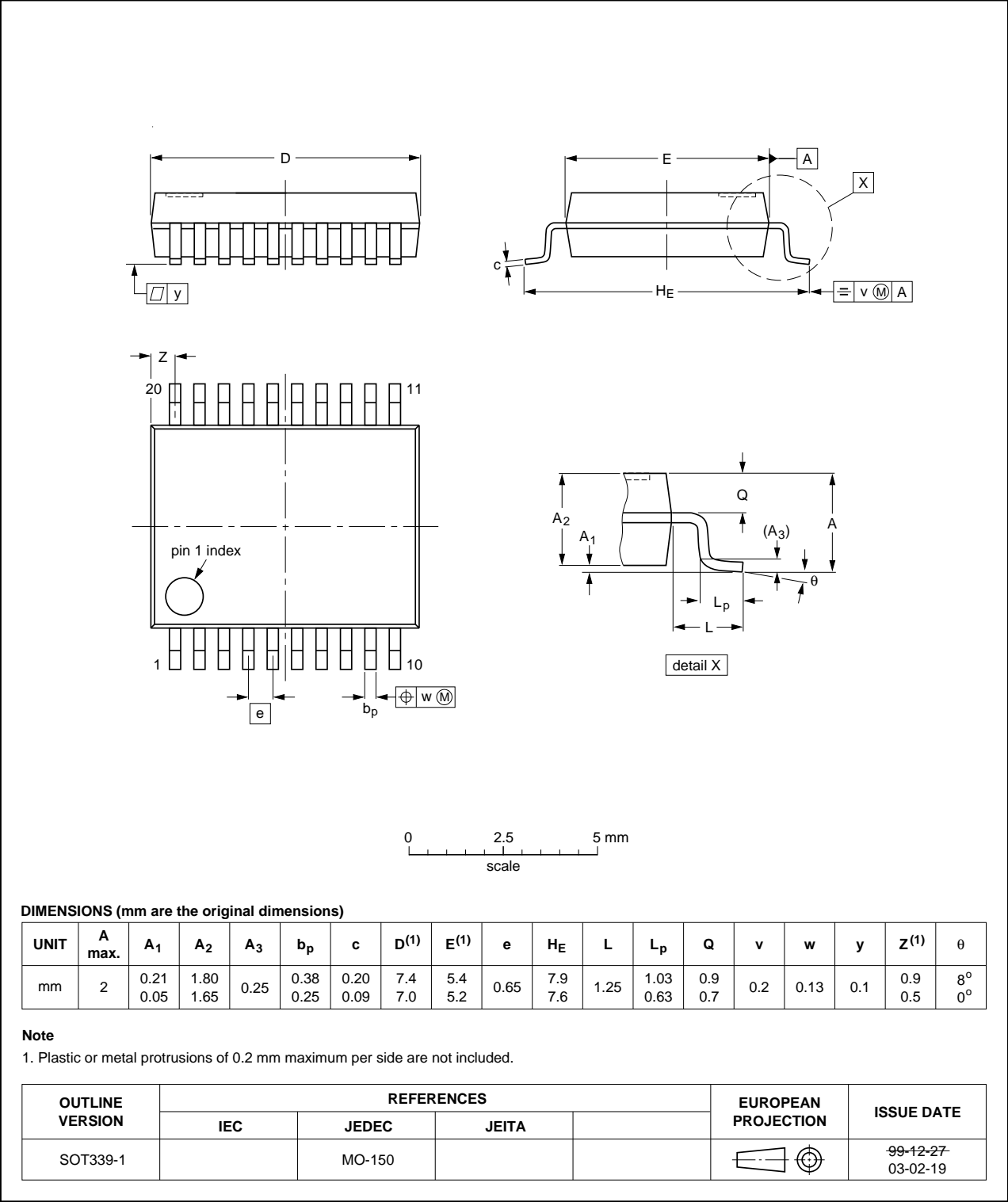


Fig 11. Package outline SOT339-1 (SSOP20)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT540 v.3	20130121	Product data sheet	-	74HC_HCT540_CNV v.2
Modifications:	<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>			
74HC_HCT540_CNV v.2	19970905	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 21 January 2013

Document identifier: 74HC\_HCT540